

OPTOLINQ BMC-1100

Black epoxy molding compound



- Excellent heat resistance
- Exceptional moldability with long spiral flow
- Excellent reliability for optoelectronic device encapsulation

OPTOLINQ BMC-1100 is a black epoxy molding compound specifically designed for the encapsulation of optoelectronic devices. With its high spiral flow, **BMC-1100** exhibits outstanding moldability, while its high thermal resistance and excellent reliability make it an ideal choice for optoelectronic device encapsulation.

Cured properties¹

Property	Value	Unit
Specific gravity	2.0±0.1	–
Hardness at 25 °C	70	Shore D
Gel time at 150 °C	25–40	s
Spiral flow at 150 °C	70–160	cm
Mold shrinkage	0.5	%
Glass transition temperature by TMA	150	°C
Coefficient of thermal expansion, α1	10–20	ppm/K
Coefficient of thermal expansion, α2	30–50	ppm/K
Flexural strength	110	MPa
Flexural modulus	15–25	GPa

¹ Samples were cured using the following parameters. In mold cure: 2 min at 175 °C, Post-mold cure: 4 h at 150 °C

² Sample thickness is 1 mm.

Recommended mold parameters

Parameter	Value	Unit
Molding temperature	175	°C
Molding pressure	10–30	MPa
Transfer time at 175 °C	40–100	s
Cure time at 175 °C	1.5–2	min
Post mold cure time at 150–175 °C	4–8	h

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Processing Instructions

- Before use, allow **BMC-1100** to reach room temperature for a minimum of 8 hours, ensuring the bag remains unopened to prevent moisture contamination.
- Apply an outer releasing agent, such as silicones or fluorinated compounds, to the mold surface to facilitate easy release from the mold dies.
- Prior to molding with **BMC-1100** or any new material, the mold should be cleaned thoroughly. For proper mold conditioning, the initial three shots should be cured for 5–10 minutes. After this initial conditioning period, you can reduce the curing time to a level that provides sufficient hot hardness for effective release.

Please note that the provided information is based on available data and typical conditions. For specific applications and detailed test results, refer to the actual test data and conduct appropriate certifications.

Storage and Handling

OPTOLINQ BMC-1100 is available in pressed pellets in a wide range of sizes to meet specific customer needs. To ensure product integrity, keep it away from oxidizing materials. For long-term storage, maintain a cold environment, ideally at -20°C or lower. The shelf life under this condition is 12 months.

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